IBM Docket No.: END920000129US1

TEN-10-5546)

06-19-2001



Name and address of receiving arty(ies): ne: INTERNATIONAL BUSINESS MACHINES CORPORATION rnal Address: Northard Road Armonk Total rumber of applications and patents involved:1 Total fee (37 CFR 3.41):
INTERNATIONAL BUSINESS MACHINES CORPORATION rnal Address: Very Corporation Set Address: Very Orchard Road A Armonk Set New York Total rame(s) & address(es) attached? Object No. Object No. Sub-Assembly And Method Object No. Object No.
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IBM Docket No.: END920000129US1 (IEN-10-5546)

ASSIGNMENT

Whereas, I

Inventor and City

WILLIAM LOUIS BRODSKY **(1)**

City of Binghamton and State of New York

and

(2) **BENSON CHAN**

City of Vestal

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(3) MICHAEL ANTHONY GAYNES

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VOYA RISTA MARKOVICH (4)

City of Endwell

County of Broome

and State of New York

have invented certain improvements in

Title

PRINTED WIRING BOARD INTERPOSER SUB-ASSEMBLY AND METHOD

Date That Inventor

and have executed, respectively, a United States patent application therefor on

Signed the

(1) M_{4Y} , 18, 2001 and (2) M_{4V} , $\frac{27}{23}$, 2001 (3) $\frac{5/50/2 \text{ cel}}{23}$, 2001 and (4) M_{4V} , M_{4V} , M_{4V} , 23, 2001 Declaration

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patent to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application. and I request the Commissioner of Patents to issue and Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

PAGE 1 of 2

PATENT REEL: 011893 FRAME: 0106

City	(1) Signed at Endicott, N.Y.	
Date	on 5/13/2001 WILLIAM LOUIS BRODSKY	_Signature)inventor
City	(2) Signed at Erdus 4 NY	
Date	on <u>5/24/31</u> BENSON CHAN	Signature)inventor
City	(3) Signed at ENDicott, NY	
Date	on 5/30/2001 Michael Conthony Hagnes (MICHAEL ANTHONY GAYNES	_Signature)Inventor
City	(4) Signed at Indicoll, V , on $\frac{V}{2}/23/01$ V . Nockon V	
Date	on $\sqrt[3]{3/0}$ V. Noekwy (VOYA RISTA MARKOVICH)	_Signature)inventor

RECORDED: 05/31/2001